

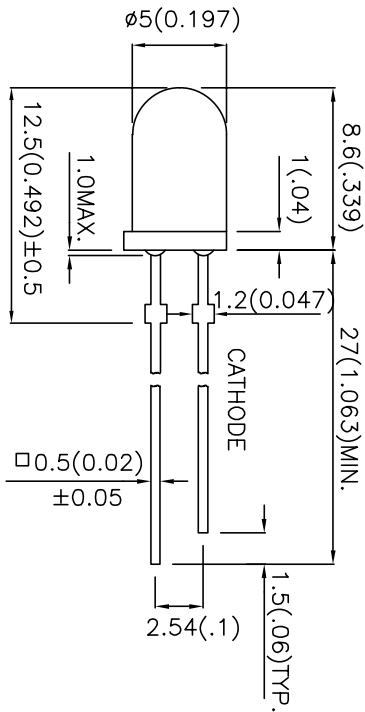


Weight: 0.30 g Unit: mm

# AND114SP (Flat)

## Standard LED

### T-1 3/4 Package (5 mm)



### Features

- Low power requirement
- Flush-mount
- All plastic molded lens
- Color: GaAsP-Red

### Optical Characteristics ( $T_a = 25^\circ\text{C}$ )

Color		Lens Desc.	Axial Luminous Intensity (mcd)		Test Condition ( $I_F$ -mA)	Viewing Angle $2\theta_{1/2}$ (deg)
LED	Lens		Min.	Typ.		
Red	Red	Diffused	20	50	10	60

### Absolute Maximum Ratings ( $T_a = 25^\circ\text{C}$ )

Characteristics	Symbol	Rating (Yellow)	Unit
Forward Current (DC)	$I_F$	30	mA
Reverse Voltage	$V_R$	5	V
Power Dissipation	$P_D$	75	mW
Operating Temperature	$T_{Opr}$	-40 to +85	$^\circ\text{C}$
Storage Temperature Range	$T_{Stg}$	-40 to +85	$^\circ\text{C}$

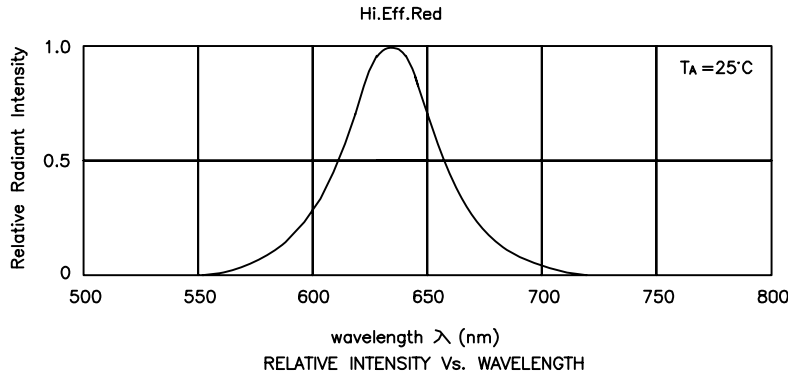
### Electro-Optical Characteristics ( $T_a = 25^\circ\text{C}$ )

Characteristics	Symbol	Test Condition	Yellow			Unit
			Min.	Typ.	Max.	
Forward Voltage	$V_F$	$I_F = 20\text{mA}$	-	2.0	2.5	V
Reverse Current	$I_R$	$V_R = 5\text{V}$	-	-	10	$\mu\text{A}$
Peak Emission Wavelength	$\lambda_p$	$I_F = 15\text{mA}$	-	627	-	nm
Spectral Line Half Width	$\lambda$	$I_F = 15\text{mA}$	-	45	-	nm

### Precaution

Please be careful of the following:

1. Soldering temperature:  $260^\circ\text{C}$  max; Soldering time: 5 sec. max; Soldering portion of lead: up to 1.6 mm from the body of the device.
2. The lead can be formed up to 5 mm from the body of the device without forming stress. Soldering should be performed after the lead forming.



### High Efficiency Red

